



**ABSTRACT**

TI Device: TPS7H5031-SEP

TI qualification testing is a risk mitigation process that is engineered to assure device longevity in customer applications. Wafer fabrication process and package level reliability are evaluated in a variety of ways that may include accelerated environmental test conditions with subsequent derating to actual use conditions. Manufacturability of the device is evaluated to verify a robust assembly flow and assure continuity of supply to customers. TI Space Enhanced Products are qualified with industry standard test methodologies performed to the intent of Joint Electron Devices Engineering Council (JEDEC) standards and procedures. Texas Instruments Space Enhanced Products meet GEIA-STD-0002-1.

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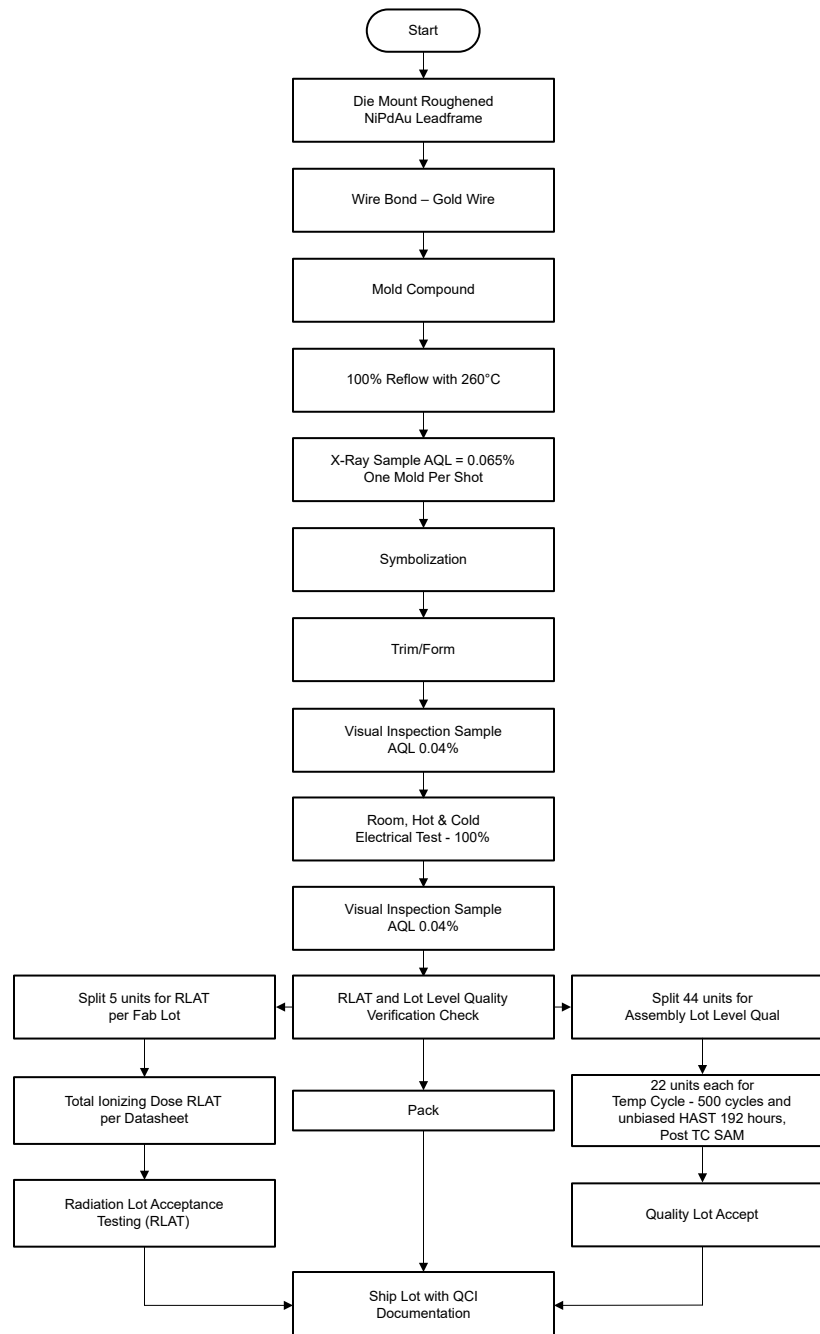
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# 1 Space Enhanced Plastic Production Flow

## 1.1 Device Introduction

TPS7H5031-SEP is a radiation tolerant device in a plastic package which is qualified and screened for space applications. The device was verified immune to 48MeV × cm<sup>2</sup>/mg at 125°C for single-event latch-up (SEL). Each fabrication lot was tested according to MIL-STD-883 for radiation lot acceptance testing (RLAT) up to 50krad(Si) at HDR, and each assembly and test lot follows the process flow shown in [TPS7H5031-SEP Space Enhanced Plastic Production Flow Chart](#). To maintain the quality of TPS7H5031-SEP, the device is qualified with Space EP requirements. See [Section 2](#) for further details.

## 1.2 TPS7H5031-SEP Space Enhanced Plastic Production Flow



**Figure 1-1. TPS7H5031-SEP Space Enhanced Plastic Production Flow Chart**

## 2 Device Qualification

The following is the device qualification summary.

### Qualification by Similarity (Qualification Family)

A new device can be qualified either by performing full scale quality and reliability tests on the actual device or using previously qualified devices through *qualification by similarity* (QBS) rules. By establishing similarity between the new device and those qualified previously, repetitive tests are eliminated, allowing for timely production release. When adopting QBS methodology, the emphasis is on qualifying the differences between a previously qualified product and the new product under consideration.

The QBS rules for a technology, product, test parameters, or package shall define which attributes are required to remain fixed for the QBS rules to apply. The attributes which are expected and allowed to vary are reviewed and a QBS plan shall be developed, based on the reliability impact assessment above, specifying what subset of the full complement of environmental stresses is required to evaluate the reliability impact of those variations. Each new device shall be reviewed for conformance to the QBS rule sets applicable to that device. See JEDEC JESD47 for more information.

**Table 2-1. Space Enhanced Products New Device Qualification Matrix**

| Note that qualification by similarity ( <i>qualification family</i> ) per JEDEC JESD47 is allowed. |   |                          |               |   |
|--|---|--------------------------|---------------|---|
| DESCRIPTION  | CONDITION   | SAMPLE SIZE USED/REJECTS | LOTS REQUIRED | TEST METHOD                                 |
| Electromigration   | -   | N/A                      | N/A           | Per TI Design Rules                         |
| Wire Bond Life   | -   | N/A                      | N/A           | Per TI Design Rules                         |
| Electrical Characterization  | TI DataSheet  | 30                       | 3             | N/A   |
| Electrostatic Discharge Sensitivity  | HBM per TI Datasheet  | 3 units/voltage          | 1             | JEDEC JS-001 or EIA/JESD22-A114             |
|  | CDM per TI Datasheet  |                          |               | JEDEC JS-002 or EIA/JESD22-C101             |
| Latch-up   | Per Technology  | 3/0                      | 1             | EIA/JESD78                                  |
| Physical Dimensions  | TI Data Sheet   | 5/0                      | 1             | EIA/JESD22- B100                            |
| Thermal impedance  | Theta-JA on board   | Per Pin-Package          | N/A           | EIA/JESD51                                  |
| Bias Life Test   | 125°C / 1000 hours or equivalent  | 77/0                     | 3             | JESD22-A108                                 |
| Extended Biased HAST   | 130°C / 85% / 192 hours   | 77/0                     | 1             | JESD22-A110/A101 <sup>(1)</sup>             |
| Unbiased HAST  | 130°C / 85% / 192 hours   | 77/0                     | 3             | JESD22-A.118 <sup>(1)</sup>                 |
| Temperature Cycle  | -65°C to +150°C non-biased for 500 cycles or equivalent                             | 77/0                     | 3             | JESD22-A104 <sup>(1)</sup>                  |
| Solderability  | Bake Preconditioning  | 22/0                     | 1             | ANSI/J-STD-002                              |
| Flammability   | Method A - UL 94V-0<br>or Method B - IEC standard 695- 2-2<br>or Method C - UL 1694 | 5/0                      | 1             | UL 94V-0<br>IEC standard 695-2-2<br>UL 1694 |
| Bond Shear   | Per wire size   | 5 units x 30/0 bonds     | 3             | JESD22-B116                                 |
| Bond Pull Strength   | Per wire size   | 5 units x 30/0 bonds     | 3             | ASTM F-459                                  |
| Die Shear  | Per die size  | 5/0                      | 3             | MIL-STD-883, TM 2019                        |
| High Temperature Storage   | 175 °C / 420 hours or equivalent  | 15/0                     | 3             | JESD22-A103                                 |
| Moisture Sensitivity   | Surface Mount Only  | 12                       | 1             | J-STD-020                                   |
| Radiation Response Characterization  | Per TI Datasheet  | -                        | 1             | Refer to Radiation Reports                  |
| Outgassing Characterization  | TML <=1% (Total Mass Lost) CVCM <=0.1% (Collected Volatile Condensable Material)    | - <sup>(2)</sup>         | 1             | ASTM E595 <sup>(2)</sup>                    |

(1) Precondition performed per JEDEC Std. 22, Method A112/A113.

(2) Outgassing test was performed on representative units. A total mass loss (TML) of 1.00% and collected volatile condensable material (CVCM) of 0.10% were used as screening levels for rejection of spacecraft materials. The outgas test was performed in a vacuum environment of less than  $5 \times 10^{-5}$  Torr according to ASTM E 595, for a duration of 24 hours, at 125°C. The TML and CVCM were measured after the test.

**Technology Family FIT / MTBF Data**

Mean Time Between Fails (MTBF) and Failures in Time (FIT) rates are device reliability statistics calculated based on data collected from TI's internal reliability testing (life test).

TI's DPPM/FIT/MTBF Estimator Search Tool reports the generic data based on technology groupings and shows conditions under which the rates were derived. All terms used in the tool and definitions can be found on the TI reliability terminology page. Failure rates are summarized by technology and mapped to the associated material part numbers. The failure rates are highly dependent on the number of units tested, therefore, it is not recommended to compare failure rates.

TI DPPM/FIT/MTBF Estimator Search Tool webpage link:

[www.ti.com/quality/docs/estimator.tsp](http://www.ti.com/quality/docs/estimator.tsp)

**Device Family Qualification Data**

TI's Qualification Summary Search Tool reports generic qualification data representative of the material sets, processes, and manufacturing sites used by the device family and may not include all of the testing performed for a specific SEP device. Please see the Space Enhanced Products New Device Qualification Matrix above for the full suite of qualification testing performed to release Space Enhanced Product devices.

TI Qualification Summary Search webpage link:

[www.ti.com/qualificationsummary/qualsumm/home](http://www.ti.com/qualificationsummary/qualsumm/home)

**Ongoing Reliability Monitoring**

TI periodically monitors the reliability of its products, wafer fab processes, and package technologies, through its Ongoing Reliability Monitor (ORM) program. The ORM program involves collecting environmental reliability stress data on representative sets of devices, processes and packages. The results from the ORM program are updated quarterly in this report.

TI Ongoing Reliability Monitoring Search webpage link:

[www.ti.com/orm/home?actionId=2801.html](http://www.ti.com/orm/home?actionId=2801.html)

For additional information or technical support please contact the [Texas Instruments Customer Support Center](#). For more information on TI Space Enhanced Products, click [here](#).

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